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**LDC1041**

SNOSC11 – MARCH 2014

## LDC1041: 8-bit Rp, 24-bit L Inductance-to-Digital Converter with SPI

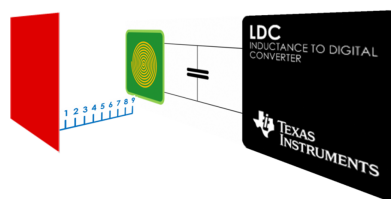
### 1 Features

- Remote sensor placement (decoupling the LDC from harsh environments)
- High durability (by virtue of contactless operation)
- Higher flexibility for system design (using coils or springs as sensors)
- Insensitive to non-conductive environmental interferers (such as dirt, dust, oil etc.)
- Magnet-free operation
- Sub-micron precision
- Supply Voltage: 5 V, typ
- Supply voltage, IO: 1.8V to 5.5V
- Stand-by current: 250uA, typ
- Rp resolution: 8-bit
- L resolution: 24-bit
- LC frequency range: 5kHz to 5MHz

#### Device Information

ORDER NUMBER	PACKAGE	BODY SIZE
LDC1041NHRT	WSO (16)	5 mm x 4 mm
LDC1041NHRR	WSO (16)	5 mm x 4 mm
LDC1041NHRJ	WSO (16)	5 mm x 4 mm

#### Axial Distance Sensing Application



### 2 Applications

- Level sensing
- Proximity sensing
- Spring motion sensing
- Lateral and angular position sensing
- Metal composition detection

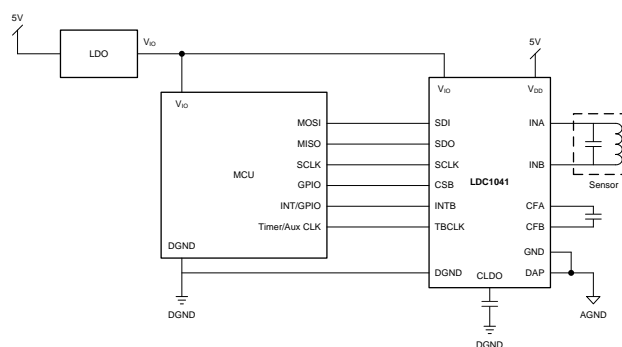
### 3 Description

Inductive sensing is a contactless, short-range sensing technology enabling high-resolution and low-cost position sensing of conductive targets, even in harsh environments. Using a coil or spring as a sensor, the LDC1041 inductance-to-digital converter provides system designers a way to achieve high performance and reliability at a lower system cost than other competing solutions.

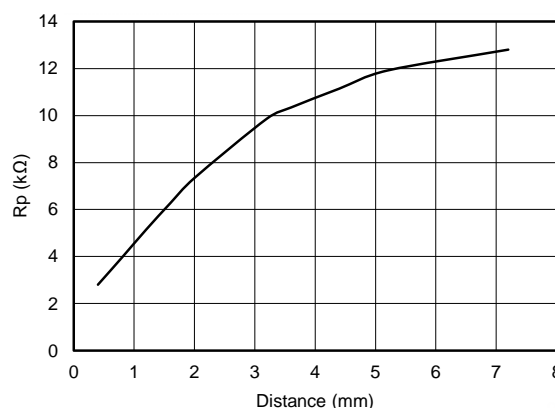
The LDC1041 is pin compatible with the LDC1000 (16-bit Rp/24-bit L) and the LDC1051 (8-bit Rp). This family of devices offers system designers different resolution options based on their application and system requirements.

The LDC1041 is available in a 5mm x 4mm WSON-16 package. Device programming via SPI allows for easy configuration using a microcontroller.

#### Application Schematic



#### Rp vs Distance With 14mm PCB Coil



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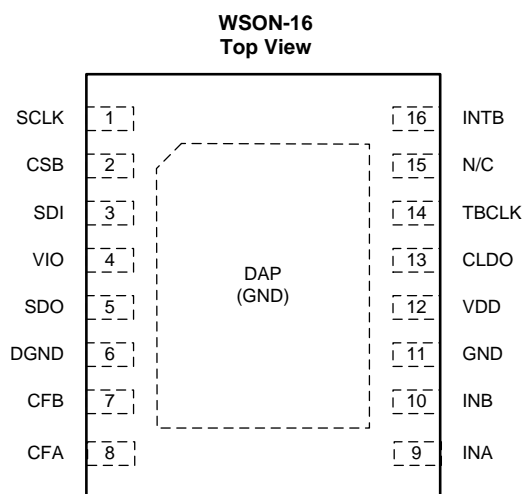
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## 4 Revision History

DATE	REVISION	NOTES
March 2014	*	Initial release.

## 5 Terminal Configuration and Functions



### Terminal Description

TERMINAL NAME	TERMINAL NO.	TERMINAL TYPE <sup>(1)</sup>	FUNCTION
SCLK	1	DO	SPI clock input. SCLK is used to clock-out/clock-in the data from/into the chip
CSB	2	DI	SPI CSB(Chip Select Bar). Multiple devices can be connected on the same SPI bus and CSB can be used to select the device to be communicated with
SDI	3	DI	SPI Slave Data In (Master Out Slave In). This should be connected to the Master Out Slave In of the master
VIO	4	P	Digital IO Supply
SDO	5	DO	SPI Slave Data Out (Master In Slave Out).It is high impedance when CSB is high
DGND	6	P	Digital ground
CFB	7	A	LDC filter capacitor
CFA	8	A	LDC filter capacitor
INA	9	A	External LC Tank. Connect to external LC tank
INB	10	A	External LC Tank. Connect to external LC tank
GND	11	P	Analog ground
VDD	12	P	Analog supply
CLDO	13	A	LDO bypass capacitor. A 56nF capacitor should be connected from this Terminal to GND
TBCLK	14	DI	External time-base clock
N/C	15	N/C	No Connection
INTB	16	DO	Configurable interrupt. This Terminal can be configured to behave in 3 different ways by programing the INT Terminal mode register. Either threshold detect, wakeup, or DRDYB
DAP	17	P	Connect to GND

(1) DO: Digital Output, DI: Digital Input, P: Power, A: Analog

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## 6 Specifications

### 6.1 Absolute Maximum Ratings<sup>(1)</sup>

	MIN	MAX	UNIT
Analog Supply Voltage ( $V_{DD} - GND$ )		6	V
IO Supply Voltage ( $V_{IO} - GND$ )		6	V
Voltage on any Analog Terminal	-0.3	$V_{DD} + 0.3$	V
Voltage on any Digital Terminal	-0.3	$V_{IO} + 0.3$	V
Input Current on INA and INB		8	mA
Junction Temperature, $T_J$ <sup>(2)</sup>		150	°C

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. Operating Ratings are conditions under which operation of the device is intended to be functional. For ensured specifications and test conditions, see the Electrical Characteristics.
- (2) The maximum power dissipation is a function of  $T_J(MAX)$ ,  $\theta_{JA}$ , and the ambient temperature,  $T_A$ . The maximum allowable power dissipation at any ambient temperature is  $PD_{MAX} = (T_J(MAX) - T_A) / \theta_{JA}$ . All numbers apply for packages soldered directly onto a PC board. The package thermal impedance is calculated in accordance with JESD 51-7.

### 6.2 Handling Ratings

		MIN	MAX	UNIT
$T_{stg}$	Storage Temperature Range	-65	150	°C
$V_{ESD}$ <sup>(1)</sup>	Human Body Model (HBM) ESD stress voltage <sup>(2)</sup>	1k	1k	V
	Charge Device Model (CDM) ESD stress voltage <sup>(3)</sup>	250	250	V

- (1) Electrostatic discharge (ESD) to measure device sensitivity and immunity to damage caused by assembly line electrostatic discharges in to the device.
- (2) Level listed above is the passing level per ANSI, ESDA, and JEDEC JS-001. JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (3) Level listed above is the passing level per EIA-JEDEC JESD22-C101. JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Analog Supply Voltage ( $V_{DD} - GND$ )	4.75	5.25	V
IO Supply Voltage ( $V_{IO} - GND$ )	1.8	5.25	V
$V_{DD} - V_{IO}$	0		V
Operating Temperature, $T_A$	-40	125	°C

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. Operating Ratings are conditions under which operation of the device is intended to be functional. For ensured specifications and test conditions, see the Electrical Characteristics.

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		NHR (16-TERMINALS)	UNIT
$\theta_{JA}$	Junction-to-ambient thermal resistance	28	°C/W

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](http://www.ti.com/lit/an/spra953).

## 6.5 Electrical Characteristics<sup>(1)</sup>

Unless otherwise specified, all limits ensured for  $T_A = T_J = 25^\circ\text{C}$ ,  $V_{DD} = 5\text{ V}$ ,  $V_{IO} = 3.3\text{ V}$ <sup>(2)</sup>

PARAMETER		TEST CONDITIONS	MIN <sup>(3)</sup>	TYP <sup>(4)</sup>	MAX <sup>(3)</sup>	UNIT	
POWER							
V <sub>DD</sub>	Analog supply voltage		4.75	5	5.25	V	
V <sub>IO</sub>	IO supply voltage	V <sub>IO</sub> ≤V <sub>DD</sub>	1.8	3.3	5.25	V	
I <sub>DD</sub>	Supply current, V <sub>DD</sub>	Does not include sensor current. <sup>(5)</sup>		1.7	2.3	mA	
I <sub>VIO</sub>	IO supply current	Static current			14	μA	
I <sub>DD_LP</sub>	Stand-by mode supply current			250		μA	
t <sub>START</sub>	Start-Up Time	From POR to ready-to-convert.		2		ms	
LDC							
f <sub>sensor_MIN</sub>	Minimum sensor frequency			5		kHz	
f <sub>sensor_MAX</sub>	Maximum sensor frequency			5		MHz	
A <sub>sensor_MIN</sub>	Minimum sensor amplitude			1		V <sub>PP</sub>	
A <sub>sensor_MAX</sub>	Maximum sensor amplitude			4		V <sub>PP</sub>	
t <sub>REC</sub>	Recovery time	Oscillation start-up time after R <sub>p</sub> under-range condition		10		1/f <sub>sensor</sub>	
R <sub>p</sub> Min	Minimum sensor R <sub>p</sub> range			798		Ω	
R <sub>p</sub> Max	Maximum Sensor R <sub>p</sub> range			3.93		MΩ	
R <sub>p</sub> Res	R <sub>p</sub> measurement resolution			8		Bits	
L Res	Inductance measurement resolution			24		Bits	
t <sub>S_MIN</sub>	Minimum response time	Minimum programmable settling time of digital filter		192 × 1 / f <sub>sensor</sub>		s	
t <sub>S_MAX</sub>	Maximum response time	Maximum programmable settling time of digital filter		6144 × 1 / f <sub>sensor</sub>		s	
EXTERNAL CLOCK							
f	External clock frequency				8	MHz	
DIGITAL I/O CHARACTERISTICS							
V <sub>IH</sub>	Logic 1 input voltage		0.8 × V <sub>IO</sub>			V	
V <sub>IL</sub>	Logic 0 input voltage			0.2 × V <sub>IO</sub>			V
V <sub>OH</sub>	Logic 1 output voltage	I <sub>SOURCE</sub> = 400 μA		V <sub>IO</sub> – 0.3			V
V <sub>OL</sub>	Logic 0 output voltage	I <sub>SINK</sub> = 400 μA		0.3			V
I <sub>IOHL</sub>	Digital IO leakage current		–500			500	nA

- (1) Electrical Characteristics Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that  $T_J = T_A$ . No specification of parametric performance is indicated in the electrical tables under conditions of internal self-heating where  $T_J > T_A$ . Absolute Maximum Ratings indicate junction temperature limits beyond which the device may be permanently degraded, either mechanically or electrically.
- (2) The maximum power dissipation is a function of  $T_J(\text{MAX})$ ,  $\theta_{JA}$ , and the ambient temperature,  $T_A$ . The maximum allowable power dissipation at any ambient temperature is  $P_{D\text{MAX}} = (T_J(\text{MAX}) - T_A) / \theta_{JA}$ . All numbers apply for packages soldered directly onto a PC board. The package thermal impedance is calculated in accordance with JESD 51-7.
- (3) Limits are specified by testing, design, or statistical analysis at  $25^\circ\text{C}$ . Limits over the operating temperature range are specified through correlations using statistical quality control (SQC) method.
- (4) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not specified on shipped production material.
- (5) LC tank current depends on the Q-factor of the tank, distance and material of the target.

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### 6.6 Timing Requirements

Unless otherwise noted, all limits specified at  $T_A = 25^\circ\text{C}$ ,  $V_{DD} = 5$ ,  $V_{IO} = 3.3$ , 10 pF capacitive load in parallel with a 10 k $\Omega$  load on the SDO terminal. Specified by design; not production tested.

PARAMETER		MIN	TYP	MAX	UNIT
$f_{\text{SCLK}}$	Serial Clock Frequency			4	MHz
$t_{\text{PH}}$	SCLK Pulse Width High	$f_{\text{SCLK}} = 4 \text{ MHz}$	$0.4 / f_{\text{SCLK}}$		s
$t_{\text{PL}}$	SCLK Pulse Width Low	$f_{\text{SCLK}} = 4 \text{ MHz}$	$0.4 / f_{\text{SCLK}}$		s
$t_{\text{SU}}$	SDI Setup Time	10			ns
$t_{\text{H}}$	SDI Hold Time	10			ns
$t_{\text{ODZ}}$	SDO Driven-to-Tristate Time	Measured at 10% / 90% point		20	ns
$t_{\text{OZD}}$	SDO Tristate-to-Driven Time	Measured at 10% / 90% point		20	ns
$t_{\text{OD}}$	SDO Output Delay Time			20	ns
$t_{\text{CSS}}$	CSB Setup Time	20			ns
$t_{\text{CSH}}$	CSB Hold Time	20			ns
$t_{\text{IAG}}$	Inter-Access Gap	100			ns
$t_{\text{DRDYB}}$	Data ready pulse width	Data ready pulse at every 1 / ODR if no data is read	$1 / f_{\text{sensor}}$		s

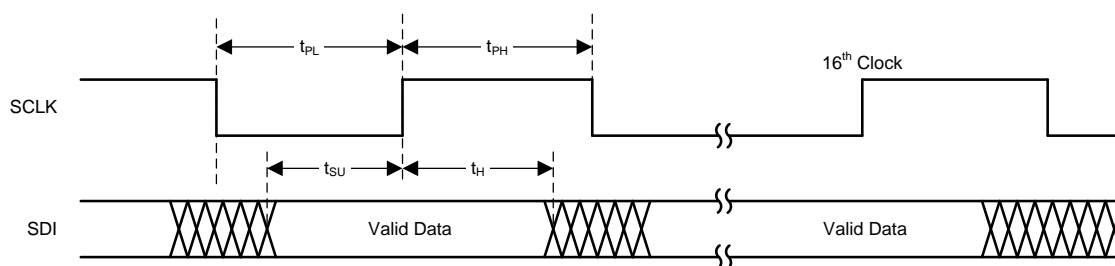


Figure 1. Write Timing Diagram

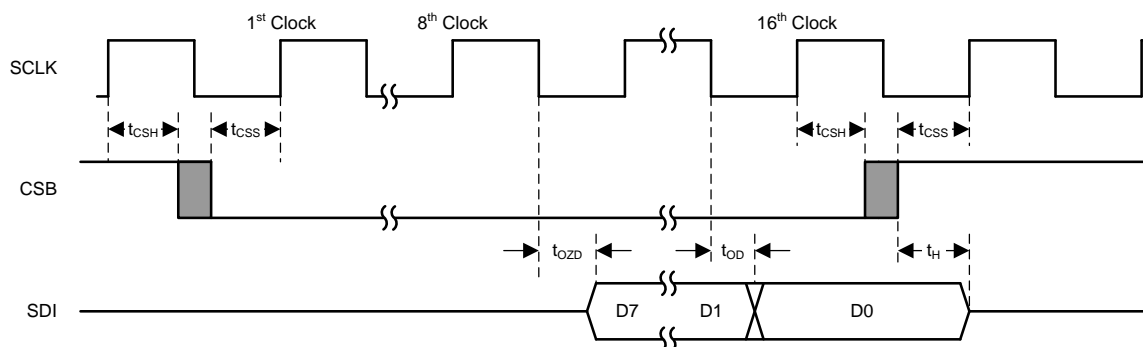
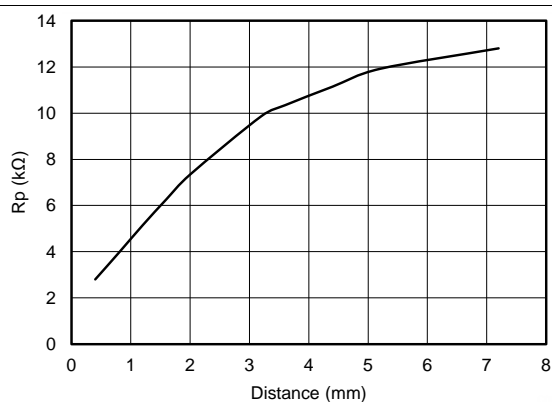


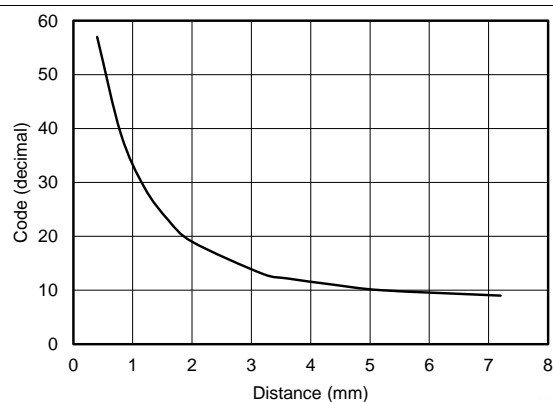
Figure 2. Read Timing Diagram

## 6.7 Typical Characteristics



Sensor Details: [Table 19](#) Rp\_MIN: 1.347 kΩ  
Target: Stainless Steel Rp\_MAX: 38.785 kΩ  
Material: Steel

**Figure 3. Rp vs Distance**



Sensor Details: [Table 19](#) Rp\_MIN: 1.347 kΩ  
Target: Stainless Steel Rp\_MAX: 38.785 kΩ  
Material: Steel

**Figure 4. Proximity Data vs Distance**



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## 7 Detailed Description

### 7.1 Overview

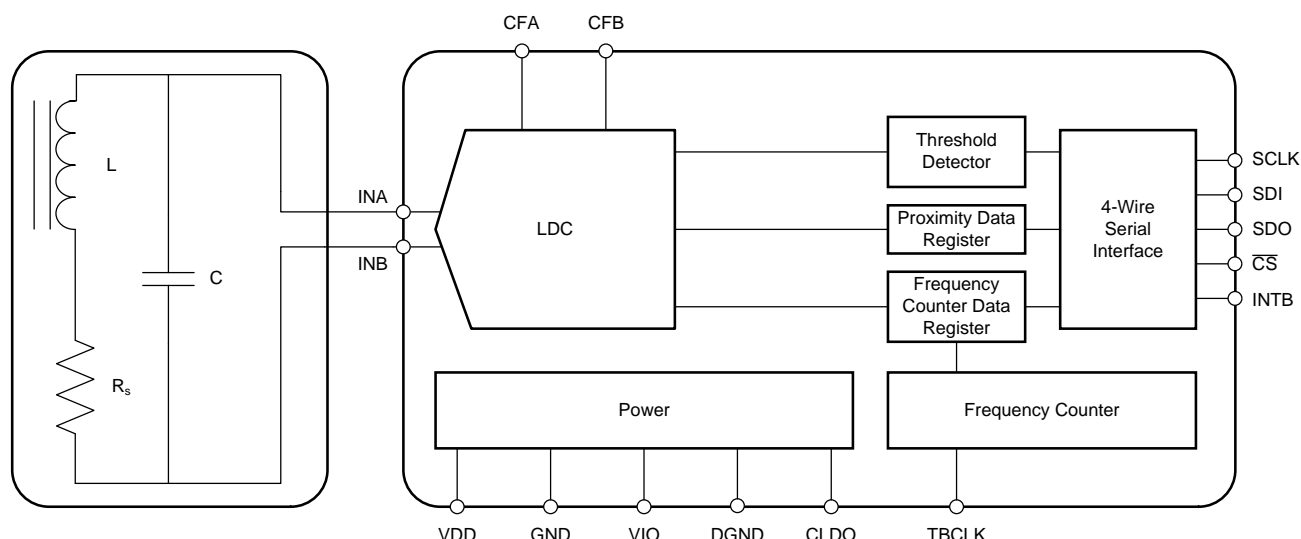
The LDC1041 is an Inductance-to-Digital Converter that simultaneously measures the impedance and resonant frequency of an LC resonator. It accomplishes this task by regulating the oscillation amplitude in a closed loop configuration to a constant level, while monitoring the energy dissipated by the resonator. By monitoring the amount of power injected into the resonator, the LDC1041 can determine the value of  $R_p$ ; it returns this as a digital value which is inversely proportional to  $R_p$ . In addition, the LDC1041 also measures the oscillation frequency of the LC circuit; this frequency is used to determine the inductance of the LC circuit. The device outputs a digital value that is inversely proportional to frequency.

The threshold detector block provides a comparator with hysteresis, with the threshold registers programmed and comparator enabled, proximity data register is compared with threshold registers and INTB pin indicates the output.

The device has a simple 4-wire SPI interface. The INTB pin provides multiple functions which are programmable with SPI.

The device has separate supplies for Analog and I/O, with analog operating at 5V and I/O at 1.8-5V. The integrated LDO needs a 56nF capacitor connected from CLDO pin to GND.

### 7.2 Functional Block Diagram

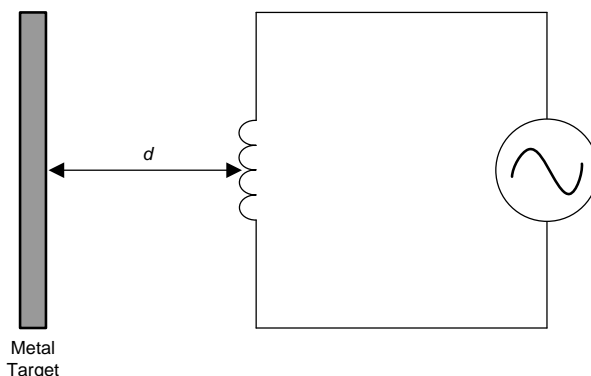


### 7.3 Feature Description

#### 7.3.1 Inductive Sensing

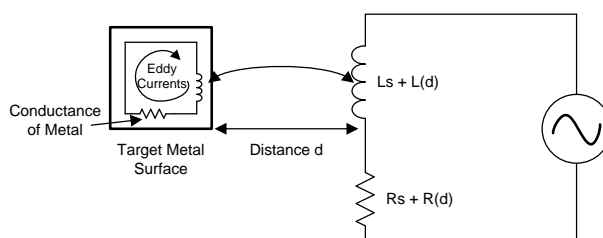
An AC current flowing through a coil will generate an AC magnetic field. If a conductive material, such as a metal target, is brought into the vicinity of the coil, this magnetic field will induce circulating currents (eddy currents) on the surface of the target. These eddy currents are a function of the distance, size, and composition of the target. The eddy currents then generate their own magnetic field, which opposes the original field generated by the coil. This mechanism is best compared to a transformer, where the coil is the primary core and the eddy current is the secondary core. The inductive coupling between both cores depends on distance and shape. Hence the resistance and inductance of the secondary core (eddy current), shows up as a distant dependent resistive and inductive component on the primary side (coil). [Figure 5](#) to [Figure 8](#) show a simplified circuit model.

## Feature Description (continued)



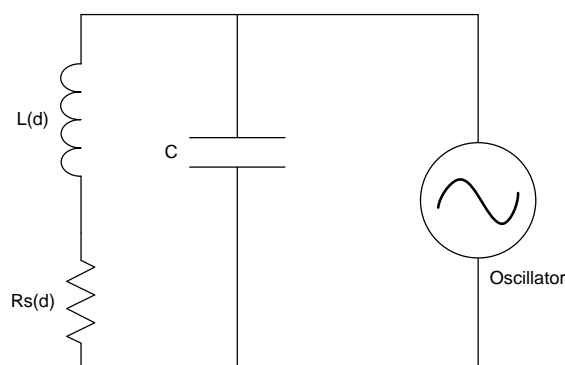
**Figure 5. Inductor With A Metal Target**

Eddy currents generated on the surface of the target can be modeled as a transformer as shown in [Figure 6](#). The coupling between the primary and secondary coils is a function of the distance and the conductor's characteristics. In [Figure 6](#), the inductance  $L_s$  is the coil's inductance, and  $R_s$  is the coil's parasitic series resistance. The inductance  $L(d)$ , which is a function of distance  $d$ , is the coupled inductance of the metal target. Likewise,  $R(d)$  is the parasitic resistance of the eddy currents and is also a function of distance.



**Figure 6. Metal Target Modeled As L And R With Circulating Eddy Currents**

Generating an alternating magnetic field with just an inductor will consume a large amount of power. This power consumption can be reduced by adding a parallel capacitor, turning it into a resonator as shown in [Figure 7](#). In this manner the power consumption is reduced to the eddy and inductor losses  $R_s + R(d)$  only.



**Figure 7. LC Tank Connected To Oscillator**

The LDC1041 doesn't measure the series resistance directly; instead it measures the equivalent parallel resonance impedance  $R_p$  (see [Figure 8](#)). This representation is equivalent to the one shown in [Figure 8](#), where the parallel resonance impedance  $R_p(d)$  is given by:

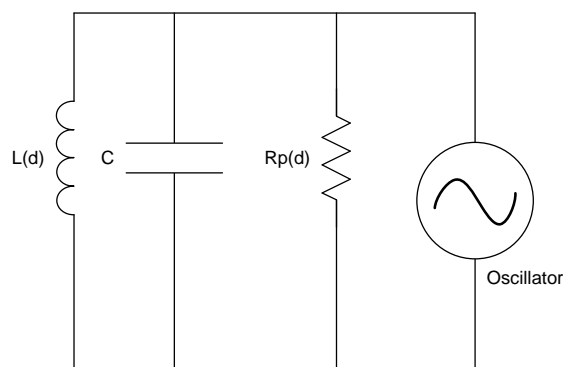
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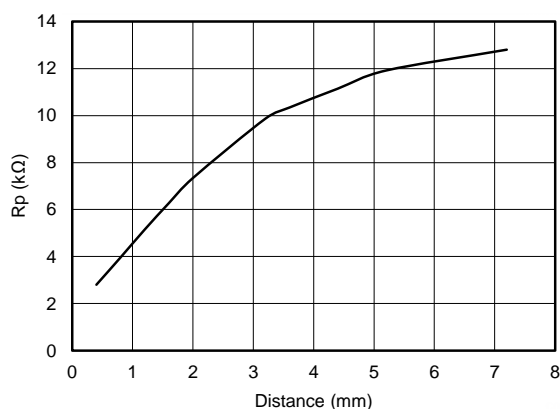
### Feature Description (continued)

$$R_p(d) = \frac{L_s + L(d)}{[R_s + R(d)] \times C} \quad (1)$$



**Figure 8. Equivalent Resistance Of  $R_s$  in Parallel With LC Tank**

Figure 9 below shows the variation in  $R_p$  as a function of distance for a 14mm diameter PCB coil (Sensor Details: Table 19). The target in this example is a section of a 2mm thick stainless steel disk.



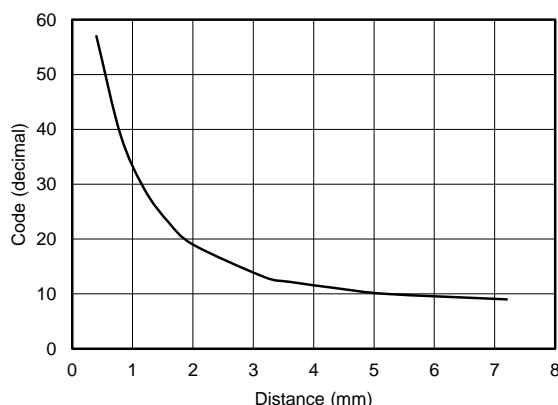
**Figure 9. Typical  $R_p$  vs Distance With 14mm PCB Coil**

## Feature Description (continued)

### 7.3.2 Measuring Rp with LDC1041

The LDC1041 supports a wide range of LC combinations, with oscillation frequencies ranging from 5kHz to 5MHz and Rp ranging from 798Ω to 3.93MΩ. This range of Rp can be viewed as the maximum input range of an ADC. As illustrated in Figure 9, the range of Rp is typically much smaller than the maximum input range supported by the LDC1041. To get better resolution in the desired sensing range, the LDC1041 offers a programmable input range through the Rp\_MIN and Rp\_MAX registers. Refer to Calculation of Rp\_MIN and Rp\_MAX below for how to set these registers.

When the sensor's resonance impedance Rp drops below the programmed Rp\_MIN, the LDC's Rp output will clip at its full scale output. This situation could, for example, happen when a target comes too close to the coil.



**Figure 10. Transfer Characteristics Of LDC1041 With Rp\_MIN= 1.347 kΩ And Rp\_MAX= 38.785 kΩ**

The resonance impedance can be calculated from the digital output code as follows:

$$R_p = \frac{R_{p\_MAX} \times R_{p\_MIN}}{R_{p\_MIN} \times (1 - Y) + R_{p\_MAX} \times Y}$$

Where:

- $Y = \text{Proximity Data} / 2^7$
- $R_{p\_MAX}$  and  $R_{p\_MIN}$  are the maximum and minimum Rp values selected in the respective registers
- Proximity data is the LDC output, register address 0x22. (2)

**Example:** If Proximity data (address 0x22) is 50, Rp\_MIN is 2.394 kΩ, and Rp\_MAX is 38.785 kΩ, the resonance impedance is given by:

$$Y = 50 / 2^7 = 0.3906$$

$$R_p = (38785 \times 2394) / (2394 \times (1 - 0.3906) + 38785 \times 0.3906) = (92851290) / (15149.421 + 1458.9036)$$

$$R_p = 5.59 \text{ k}\Omega$$

### 7.3.3 Measuring Inductance with LDC1041

LDC1041 measures the sensor's frequency of oscillation using a frequency counter. The frequency counter timing is set by an external clock applied on TBCLK terminal. The sensor frequency can be calculated from the frequency counter register value (see registers 0x23 through 0x25) as follows:

$$\text{Sensor frequency, } f_{\text{sensor}} = \frac{1}{3} \times \frac{F_{\text{ext}}}{F_{\text{count}}} \times \text{Response time}$$

where

- $F_{\text{ext}}$  is the frequency of the external clock
- $F_{\text{count}}$  is the value obtained from the Frequency Counter Data register (address 0x23, 0x24, 0x25)
- Response Time is the programmed response time (see LDC configuration register, address 0x04) (3)

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### Feature Description (continued)

The sensor inductance can be determined by:

$$L = \frac{1}{C \times (2\pi \times f_{\text{sensor}})^2}$$

where

- C is the parallel capacitance of the resonator (4)

**Example:** If  $f_{\text{ext}}=6\text{MHz}$ , Response time=6144,  $C=100\text{pF}$  and measured  $F_{\text{count}}=3000$  (dec) (address 0x23 through 0x25)

$$f_{\text{sensor}} = (1/3) \times (6000000/3000) \times (6144) = 4.096\text{MHz}$$

$$\text{Now using, } L = \frac{1}{C \times (2\pi \times f_{\text{sensor}})^2}$$

Inductance,  $L = 15.098 \mu\text{H}$

The accuracy of measurement largely depends upon the choice of the external time-base clock (TBCLK). A higher frequency will provide better measurement accuracy.

## 7.4 Device Functional Modes

### 7.4.1 Power Modes

The LDC1041 has two power modes:

1. Active Mode : In this mode the Proximity data and frequency data conversion is enabled.
2. Stand-by Mode: This is the default mode on device power-up. In this mode conversion is disabled.

### 7.4.2 INTB Pin Modes

The INTB terminal is a configurable output terminal which can be used to drive an interrupt on an MCU. The LDC1041 provides three different modes on INTB terminal:

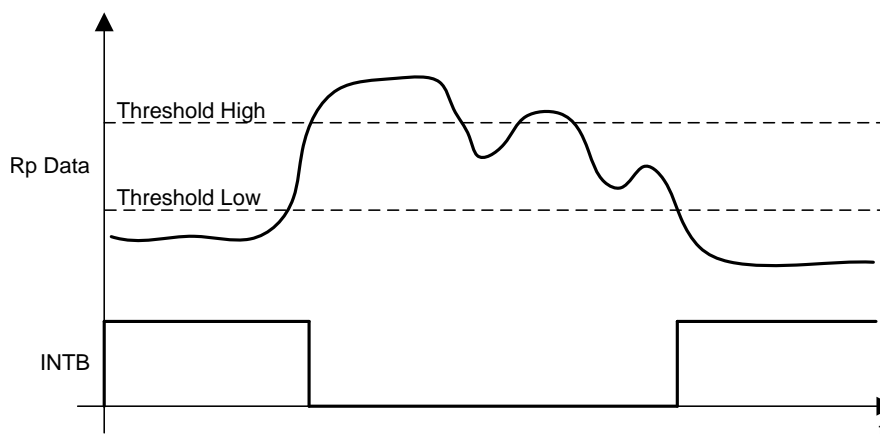
1. Comparator Mode
2. Wake-Up Mode
3. DRDY Mode

LDC1041 has built-in High and Low trigger threshold registers which can be used as a comparator with programmable hysteresis or in a special mode which can be used to wake-up an MCU. These modes are explained in detail below.

#### 7.4.2.1 Comparator Mode

In the Comparator mode, the INTB terminal is asserted or deasserted when the proximity register value increases above Threshold High or decreases below Threshold Low registers respectively. In this mode, the LDC1041 essentially behaves as a proximity switch with programmable hysteresis.

## Device Functional Modes (continued)

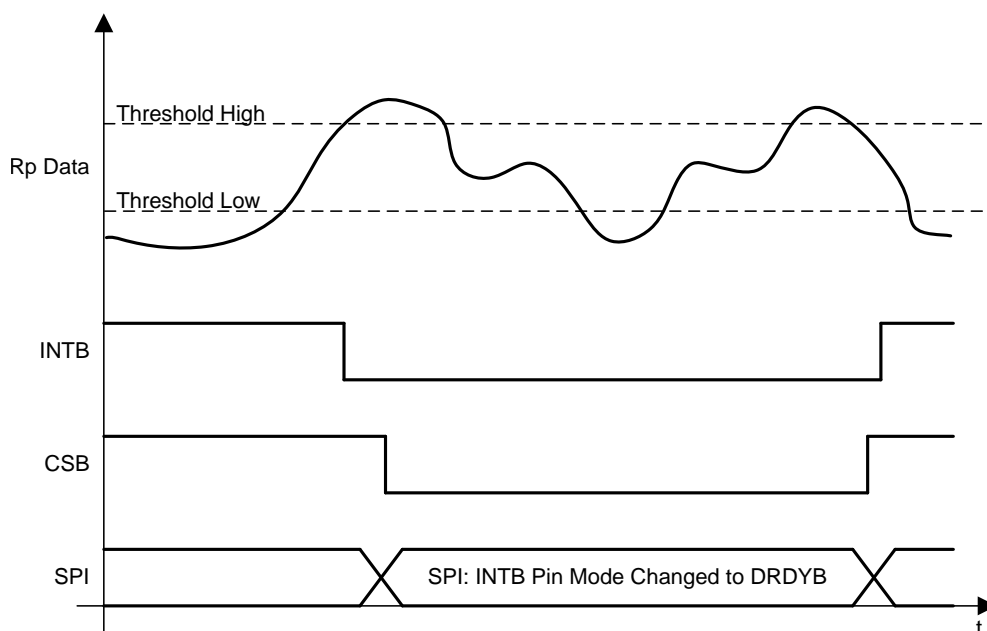


**Figure 11. Behavior Of INTB Terminal In Comparator Mode**

### 7.4.2.2 Wake-Up Mode

In Wake-Up mode, the INTB terminal is asserted when proximity register value increases above Threshold High and de-asserted when wake-up mode is disabled in INTB terminal mode register.

This mode can be used to wake-up an MCU from sleep, to conserve power.



**Figure 12. Behavior Of INTB Terminal In Wake-Up Mode**

### 7.4.2.3 DRDYB Mode

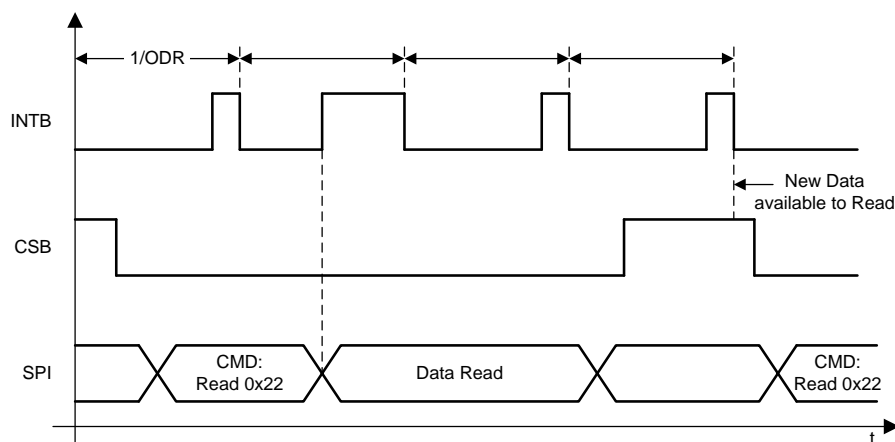
In DRDY(Data Ready) mode, the INTB terminal is asserted every time the conversion data is available and de-asserted once the read command on register 0x22 is registered internally; if the read is in progress, the terminal is pulsed instead. The valid condition for new data availability is CSB high and DRDYB falling edge.

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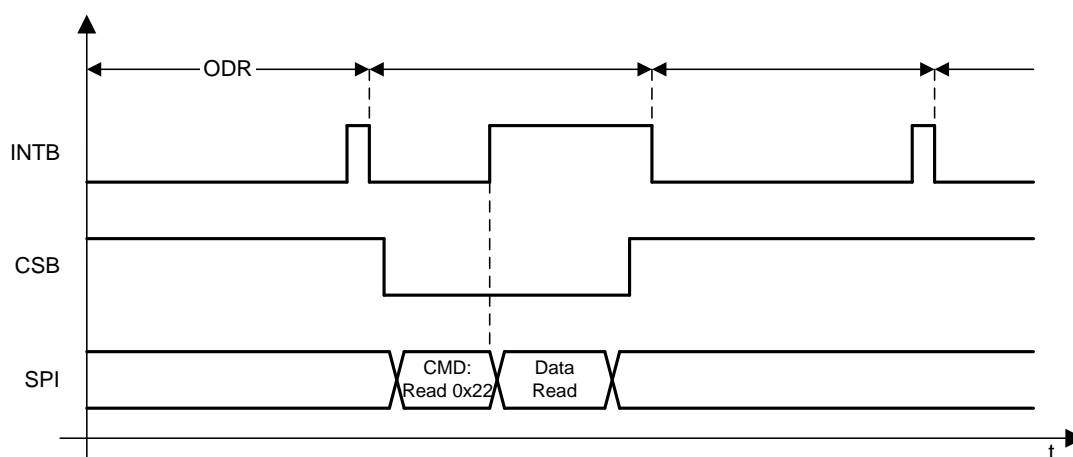
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### Device Functional Modes (continued)



**Figure 13. Behavior of INTB Terminal in DRDYB Mode with SPI Extending Beyond Subsequent Conversions**



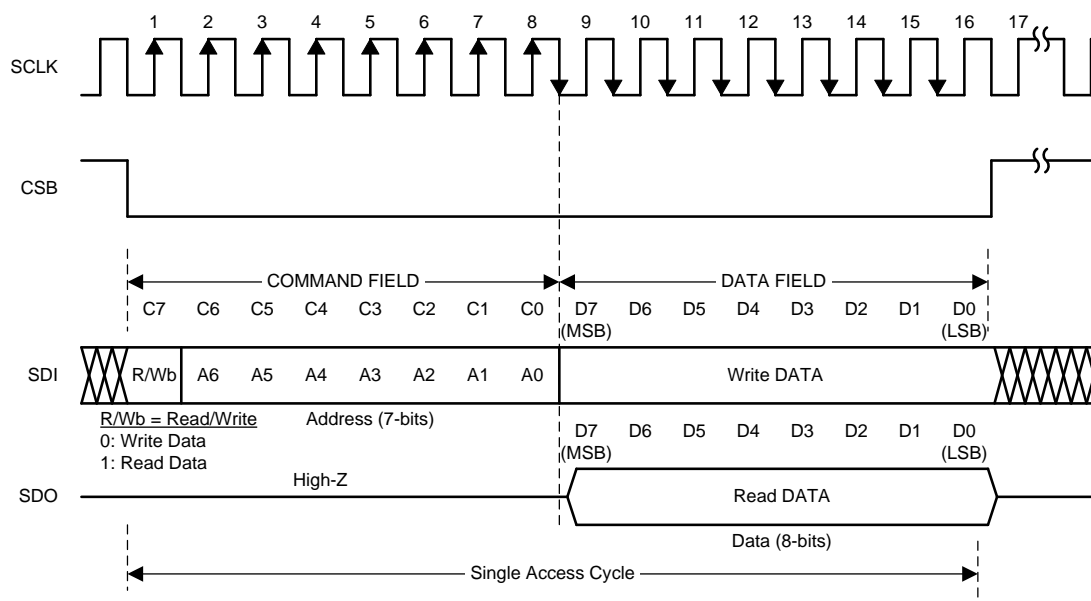
**Figure 14. Behavior Of INTB Terminal In DRDYB Mode with SPI Reading The Data Within Subsequent Conversion**

## 7.5 Programming

The LDC1041 utilizes a 4-wire SPI to access control and data registers. The LDC1041 is an SPI slave device and does not initiate any transactions.

### 7.5.1 SPI Description

A typical serial interface transaction begins with an 8-bit instruction, which is comprised of a read/write bit (MSB, R=1) and a 7-bit address of the register, followed by a data field which is typically 8 bits. However, the data field can be extended to a multiple of 8 bits by providing sufficient SPI clocks. Refer to the [Extended SPI Transactions](#) section below.



**Figure 15. Serial Interface Protocol**

Each assertion of CSB starts a new register access. The R/Wb bit in the command field configures the direction of the access; a value of 0 indicates a write operation and a value of 1 indicates a read operation. All output data is driven on the falling edge of the serial clock (SCLK), and all input data is sampled on the rising edge of the serial clock (SCLK). Data is written into the register on the rising edge of the 16th clock. It is required to deassert CSB after the 16th clock; if CSB is deasserted before the 16th clock, no data write will occur.

#### 7.5.1.1 Extended SPI Transactions

A transaction may be extended to multiple registers by keeping the CSB asserted beyond the initial 16 clocks. In this mode, the register addresses increment automatically. CSB must be asserted during  $8 \times (1+N)$  clock cycles of SCLK, where N is the amount of bytes to write or read during the transaction.

During an extended read access, SDO outputs the register contents every 8 clock cycles after the initial 8 clocks of the command field. During an extended write access, the data is written to the registers every 8 clock cycles after the initial 8 clocks of the command field.

Extended transactions can be used to read 8-bits of Proximity data and 24-bits of frequency data in a single SPI transaction by initiating a read from the register 0x22.



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## 7.6 Register Map and Description

**Table 1. Register Map**<sup>(1)(2)(3)</sup>

Register Name	Address	Direction	Default	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Device ID	0x00	RO	0x84	Device ID							
Rp_MAX	0x01	R/W	0x0E	Rp Maximum							
Rp_MIN	0x02	R/W	0x14	Rp Minimum							
Watchdog Timer Frequency	0x03	R/W	0x45	Min Sensor Frequency							
LDC Configuration	0x04	R/W	0x1B	Reserved(000)			Amplitude		Response Time		
Reserved	0x05	RO	0x01	Reserved(00000001)							
Reserved	0x06	R/W	0xFF	Reserved							
Comparator Threshold High MSB	0x07	R/W	0xFF	Threshold High MSB							
Reserved	0x08	R/W	0x00	Reserved							
Comparator Threshold Low MSB	0x09	R/W	0x00	Threshold Low MSB							
INTB Terminal Configuration	0x0A	R/W	0x00	Reserved(00000)					INTB_MODE		
Power Configuration	0x0B	R/W	0x00	Reserved(0000000)							PWR_MODE
Status	0x20	RO		OSC Dead	DRDYB	Wake-up	Comparator	Do Not Care			
Reserved	0x21	RO		Reserved(00000000)							
Proximity Data	0x22	RO		Proximity Data							
Frequency Counter Data LSB	0x23	RO		FCOUNT LSB							
Frequency Counter Data Mid-Byte	0x24	RO		FCOUNT Mid Byte							
Frequency Counter Data MSB	0x25	RO		FCOUNT MSB							

- (1) Values of register fields which are unused should be set to default values only.  
 (2) Registers 0x01 through 0x05 are Read Only when the part is awake (PWR\_MODE bit is SET)  
 (3) R/W: Read/Write. RO: Read Only. WO: Write Only.

**Table 2. Revision ID**

Address = 0x00, Default=0x84, Direction=RO		
Bit Field	Field Name	Description
7:0	Revision ID	Revision ID of Silicon.

**Table 3. Rp\_MAX**

Address = 0x01, Default=0x0E, Direction=R/W		
Bit Field	Field Name	Description
7:0	Rp Maximum	Maximum Rp that LDC1041 needs to measure. Configures the input dynamic range of LDC1041. See Table 4 for register settings.

**Table 4. Register Settings for Rp\_MAX**

Register setting	Rp (kΩ)
0x00	3926.991
0x01	3141.593
0x02	2243.995
0x03	1745.329
0x04	1308.997
0x05	981.748
0x06	747.998
0x07	581.776
0x08	436.332
0x09	349.066
0x0A	249.333
0x0B	193.926
0x0C	145.444
0x0D	109.083
0x0E	83.111
0x0F	64.642
0x10	48.481
0x11	38.785
0x12	27.704
0x13	21.547
0x14	16.160
0x15	12.120
0x16	9.235
0x17	7.182
0x18	5.387
0x19	4.309
0x1A	3.078
0x1B	2.394
0x1C	1.796
0x1D	1.347
0x1E	1.026
0x1F	0.798

**Table 5. Rp\_MIN**

Address = 0x02, Default=0x14, Direction=R/W		
Bit Field	Field Name	Description
7:0	Rp Minimum	Minimum Rp that LDC1041 needs to measure. Configures the input dynamic range of LDC1041. See <a href="#">Table 6</a> for register settings. <sup>(1)</sup>

(1) This Register needs a mandatory write as it defaults to 0x14.

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**Table 6. Register Settings for Rp\_MIN**

Register setting	Rp (kΩ)
0x20	3926.991
0x21	3141.593
0x22	2243.995
0x23	1745.329
0x24	1308.997
0x25	981.748
0x26	747.998
0x27	581.776
0x28	436.332
0x29	349.066
0x2A	249.333
0x2B	193.926
0x2C	145.444
0x2D	109.083
0x2E	83.111
0x2F	64.642
0x30	48.481
0x31	38.785
0x32	27.704
0x33	21.547
0x34	16.160
0x35	12.120
0x36	9.235
0x37	7.182
0x38	5.387
0x39	4.309
0x3A	3.078
0x3B	2.394
0x3C	1.796
0x3D	1.347
0x3E	1.026
0x3F	0.798

**Table 7. Watchdog Timer Frequency**

Address = 0x03, Default=0x45, Direction=R/W		
Bit Field	Field Name	Description
7:0	Min Sensor Frequency	<p>Sets the watchdog timer. The Watchdog timer is set based on the lowest sensor frequency.</p> $N = 68.94 \times \log_{10} \left( \frac{F}{2500} \right)$ <p>where</p> <ul style="list-style-type: none"> <li>F is the sensor frequency</li> </ul> <p>Example:            If Sensor frequency is 1Mhz            Min Sensor Frequency=68.94*log10(1M/2500)=Round to nearest integer(179.38)=179</p> <p>(5)</p>

Table 8. LDC Configuration

Address = 0x04, Default=0x1B, Direction=R/W		
Bit Field	Field Name	Description
7:5	Reserved	Reserved to 0
4:3	Amplitude	Sets the oscillation amplitude 00:1V 01:2V 10:4V 11:Reserved
2:0	Response Time	000: Reserved 001: Reserved 010: 192 011: 384 100: 768 101: 1536 110: 3072 111: 6144

Table 9. Comparator Threshold High MSB

Address = 0x07, Default=0xFF, Direction=R/W		
Bit Field	Field Name	Description
7:0	Threshold High	Threshold High Register.

Table 10. Comparator Threshold Low MSB

Address = 0x09, Default=0x00, Direction=R/W		
Bit Field	Field Name	Description
7:0	Threshold Low	Threshold Low Register.

Table 11. INTB Terminal Configuration

Address = 0x0A, Default=0x00, Direction=R/W		
Bit Field	Field Name	Description
7:3	Reserved	Reserved to 0
2:0	Mode	000: All modes disabled 001: Wake-up Enabled on INTB terminal 010: INTB terminal indicates the status of Comparator output 100: DRDYB Enabled on INTB terminal All other combinations are Reserved

Table 12. Power Configuration

Address = 0x0B, Default=0x00, Direction=R/W		
Bit Field	Field Name	Description
7:1	Reserved	Reserved to 0
0	PWR_MODE	0:Stand-By mode 1:Active Mode. Conversion is Enabled Refer to <a href="#">Power Modes</a> for more details.

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**Table 13. Status**

Address = 0x20, Default=NA, Direction=RO		
Bit Field	Field Name	Description
7	OSC status	1:Indicates oscillator overloaded and stopped 0:Oscillator working
6	Data Ready	1:No new data available 0:Data is ready to be read
5	Wake-up	1:Wake-up disabled 0:Wake-up triggered. Proximity data is more than Threshold High value.
4	Comparator	1:Proximity data is less than Threshold Low value 0:Proximity data is more than Threshold High value
3:0	Do not Care	

**Table 14. Proximity Data**

Address = 0x22, Default=NA, Direction=RO		
Bit Field	Field Name	Description
7:0	Proximity data	Proximity data

**Table 15. Frequency Counter LSB**

Address = 0x23, Default=NA, Direction=RO		
Bit Field	Field Name	Description
7:0	FCOUNT LSB (FCOUNT[7:0])	LSB of Frequency Counter. Sensor frequency can be calculated using the output data rate. Please refer to the <a href="#">Measuring Inductance with LDC1041</a> .

**Table 16. Frequency Counter Mid-Byte**

Address = 0x24, Default=NA, Direction=RO		
Bit Field	Field Name	Description
7:0	FCOUNT Mid byte (FCOUNT[15:8])	Middle Byte of Output data rate

**Table 17. Frequency Counter MSB**

Address = 0x25, Default=NA, Direction=RO		
Bit Field	Field Name	Description
7:0	FCOUNT MSB (FCOUNT[23:16])	MSB of Output data rate

Conversion data is updated to these registers only when a read is initiated on 0x22 register. If the read is delayed between subsequent conversions, these registers are not updated until another read is initiated on 0x22.

## 8 Applications and Implementation

### 8.1 Application Information

#### 8.1.1 Calculation of Rp\_MIN and Rp\_MAX

Different sensing applications may have a different range of the resonance impedance Rp to measure. The LDC1041 measurement range of Rp is controlled by setting 2 registers – Rp\_MIN and Rp\_MAX. For a given application, Rp must never be outside the range set by these register values, otherwise the measured value will be clipped. For optimal sensor resolution, the range of Rp\_MIN to Rp\_MAX should not be unnecessarily large. The following procedure is recommended to determine the Rp\_MIN and Rp\_MAX register values.

##### 8.1.1.1 Setting Rp\_MAX

Rp\_MAX sets the upper limit of the LDC1041 resonant impedance input range.

- Configure the sensor such that the eddy current losses are minimized. As an example, for a proximity sensing application, set the distance between the sensor and the target to the maximum sensing distance.
- Measure the resonant impedance Rp using an impedance analyzer.
- Multiply Rp by 2 and use the next higher value from [Table 4](#).

Note that setting Rp\_MAX to a value not listed in [Table 4](#) can result in indeterminate behavior.

##### 8.1.1.2 Setting Rp\_MIN

Rp\_MIN sets the lower limit of the LDC1041 resonant impedance input range.

- Configure the sensor such that the eddy current losses are maximized. As an example, for a proximity sensing application, set the distance between the sensor and the metal target to the minimum sensing distance.
- Measure the resonant impedance Rp using an impedance analyzer.
- Divide the Rp value by 2 and then select the next lower Rp value from [Table 6](#).

Note that setting Rp\_MIN to a value not listed on [Table 6](#) can result in indeterminate behavior. In addition, Rp\_MIN powers on with a default value of 0x14 which must be set to a value from [Table 6](#) prior to powering on the LDC.

#### 8.1.2 Output Data Rate

Output data rate of LDC1041 depends on the sensor frequency,  $f_{\text{sensor}}$  and 'Response Time' field in LDC Configuration register(Address:0x04).

$$\text{Output Data Rate} = \frac{f_{\text{sensor}}}{\left( \frac{\text{Response time}}{3} \right)} \quad (6)$$

#### 8.1.3 Choosing Filter Capacitor (CFA and CFB Terminals)

The Filter capacitor is critical to the operation of the LDC1041. The capacitor should be low leakage, temperature stable, and it must not generate any piezoelectric noise (the dielectrics of many capacitors exhibit piezoelectric characteristics and any such noise is coupled directly through Rp into the converter). The optimal capacitance values range from 20pF to 100nF. The value of the capacitor is based on the time constant and resonating frequency of the LC tank.

If a ceramic capacitor is used, then a C0G (or NP0) grade dielectric is recommended; the voltage rating should be  $\geq 10V$ . The traces connecting CFA and CFB to the capacitor should be as short as possible to minimize any parasitics.

For optimal performance, the chosen filter capacitor, connected between terminals CFA and CFB, needs to be as small as possible, but large enough such that the active filter does not saturate. The size of this capacitor depends on the time constant of the sense coil, which is given by  $L/R_s$ , ( $L$ =inductance,  $R_s$ =series resistance of the inductor at oscillation frequency). The larger this time constant, the larger filter capacitor is required. Hence, this time constant reaches its maximum when there is no target present in front of the sensing coil.

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### Application Information (continued)

The following procedure can be used to find the optimal filter capacitance:

1. Start with a large filter capacitor. For a ferrite core coil, 10nF is usually large enough. For an air coil or PCB coil, 100pF is usually large enough.
2. Power on the LDC and set the desired register values. Minimize the eddy currents losses. This is done by minimizing the amount of conductive target covering the sensor. For an axial sensing application, the target should be at farthest distance from coil. For a lateral or angular position application, the target coverage of the coil should be minimized.
3. Observe the signal on the CFB terminal using a scope. Since this node is very sensitive to capacitive loading, it is recommended to use an active probe. As an alternative, a passive probe with a 1kΩ series resistance between the tip and the CFB terminal can be used.
4. Vary the values of the filter capacitor until that the signal observed on the CFB terminal has an amplitude of approximate 1V peak-to-peak. This signal scales linearly with the reciprocal of the filter capacitance. For example, if a 100pF filter capacitor is applied and the signal observed on the CFB terminal has a peak-to-peak value of 200mV, the desired 1V peak-to-peak value is obtained using a  $200\text{mV} / 1\text{V} * 100\text{pF} = 20\text{pF}$  filter capacitor.

## 8.2 Typical Applications

### 8.2.1 Axial Distance Sensing Using a PCB Sensor with LDC1041

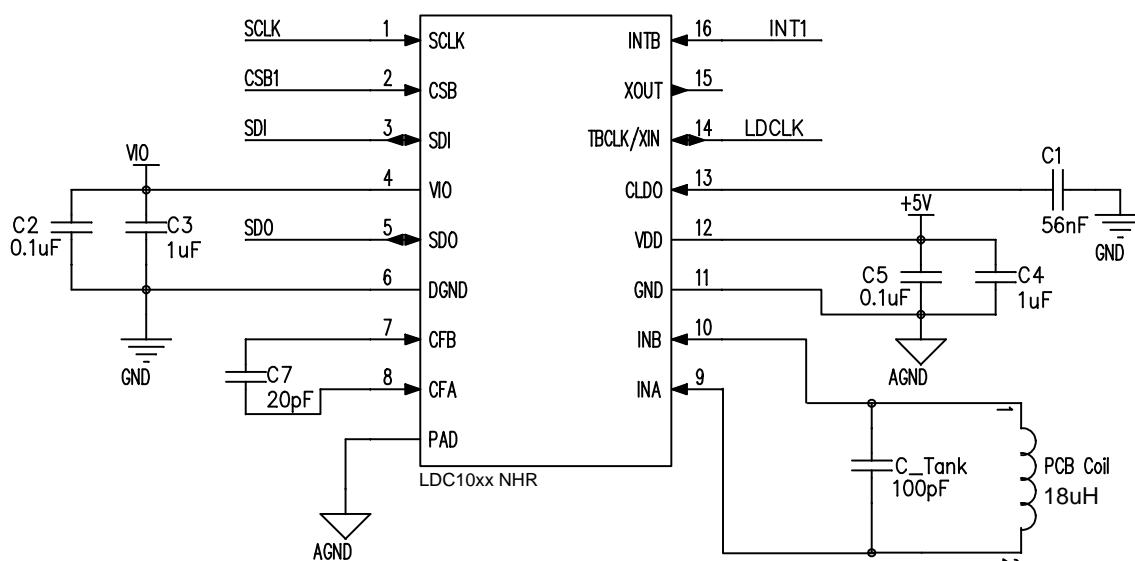


Figure 16. Typical Application Schematic, LDC10xx

#### 8.2.1.1 Design Requirements

For this design example, use the following as the input parameters.

Table 18. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Minimum sensing distance	1 mm
Maximum sensing distance	8 mm
Output data rate	78 KSPS (Max data rate with LDC10xx series)
Number of PCB layers for sensor	2 layers

### 8.2.1.2 Detailed Design Procedure

#### 8.2.1.2.1 Sensor and Target

In this example, consider a sensor with the below characteristics.

**Table 19. Sensor Characteristics**

PARAMETER	VALUE
Layers	2
Thickness of copper	1 Oz
Coil shape	Circular
Number of turns	23
Trace thickness	4 mil
Trace spacing	4 mil
PCB core material	FR4
Rp @ 1 mm	5 kΩ
Rp @ 8 mm	12.5 kΩ
Nominal Inductance	18 μH

Target material used is stainless steel

#### 8.2.1.2.2 Calculating Sensor Capacitor

Sensor frequency depends on various factors in the application. In this example since one of the design parameter is to achieve output data rate of 78 KSPS, sensor frequency can be calculated as below.

$$\text{Output Data Rate} = \frac{f_{\text{sensor}}}{\left( \frac{\text{Response time}}{3} \right)} \quad (7)$$

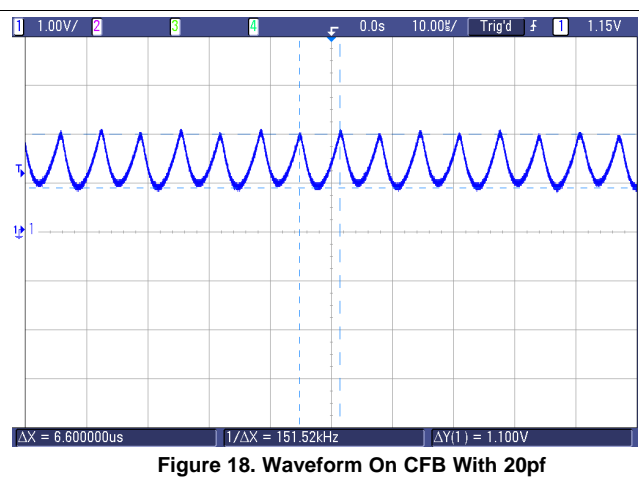
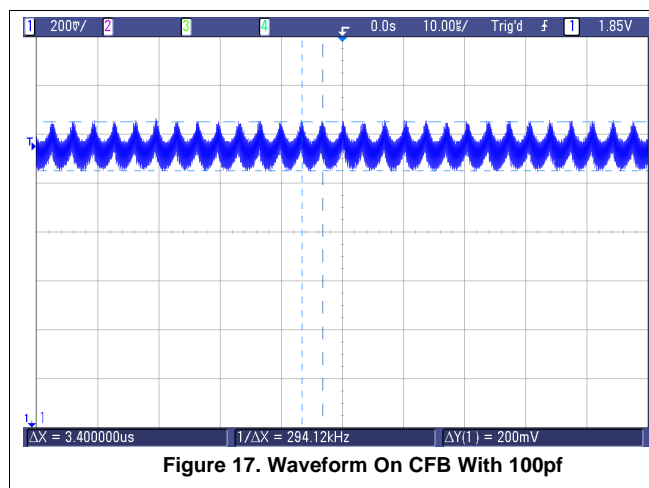
With the lowest Response time of 192 and output data rate of 78 KSPS, sensor frequency calculated using the above formula is 4.99 MHz.

Now, using the below formula sensor capacitor is calculated to be 55 pF with a sensor inductance of 18 μH

$$L = \frac{1}{C \times (2\pi \times f_{\text{sensor}})^2} \quad (8)$$

#### 8.2.1.2.3 Choosing Filter Capacitor

Using the steps given in [Choosing Filter Capacitor \(CFA and CFB Terminals\)](#) filter capacitor for the example sensor is 20 pF. Below waveform shows the pattern on CFB pin with 100 pF and 20 pF filter capacitor.





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### 8.2.1.2.4 Setting Rp\_MIN and Rp\_MAX

Calculating value for Rp\_MAX Register : Rp at 8mm is 12.5kΩ,  $12500 \times 2 = 25000$ . In Table 4, then 27.704 kΩ is the nearest value larger than 25kΩ; this corresponds to Rp\_MAX value of 0x12

Calculating value for Rp\_MIN Register : Rp at 1mm is 5kΩ,  $5000/2 = 2500$ . In Table 6, 2.394kΩ is the nearest value lower than 2.5kΩ; this corresponds to Rp\_MIN value of 0x3B

### 8.2.1.2.5 Calculating Minimum Sensor Frequency

Using,

$$N = 68.94 \times \log_{10} \left( \frac{F}{2500} \right) \quad (9)$$

N is 227.51, round off to 228 decimal. This value has to be written into Watchdog Timer Register, which is used to wake up the internal circuit when the sensor is saturated.

### 8.2.1.3 Application Curves

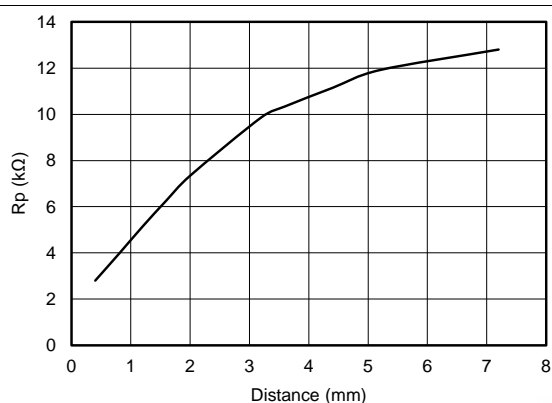


Figure 19. Rp vs Distance

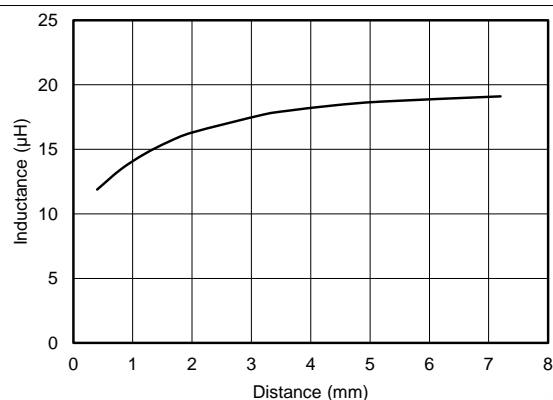
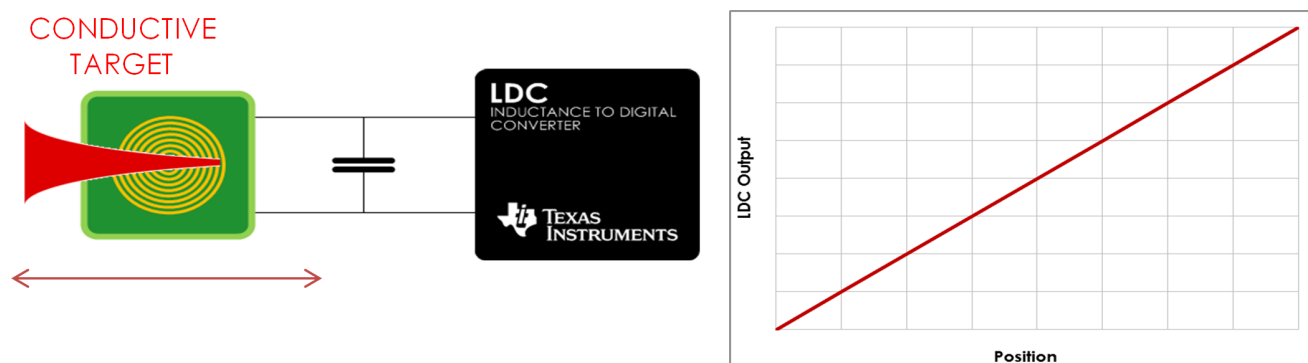


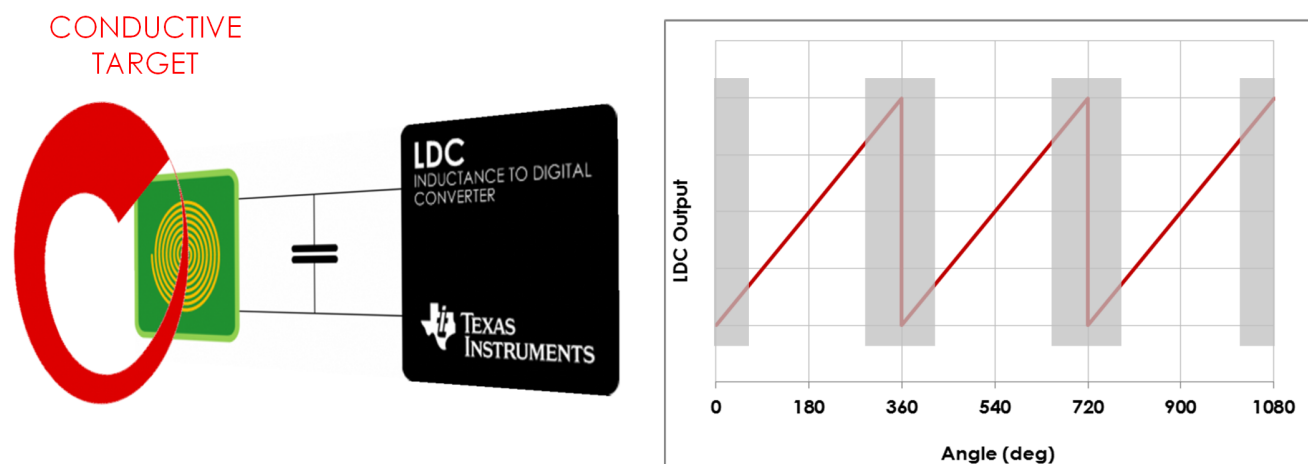
Figure 20. Inductance vs Distance

## 8.2.2 Linear Position Sensing Application Diagram



**Figure 21. Linear Position Sensing**

## 8.2.3 Angular Position Sensing Application Diagram



**Figure 22. Angular Position Sensing**

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## 9 Power Supply Recommendations

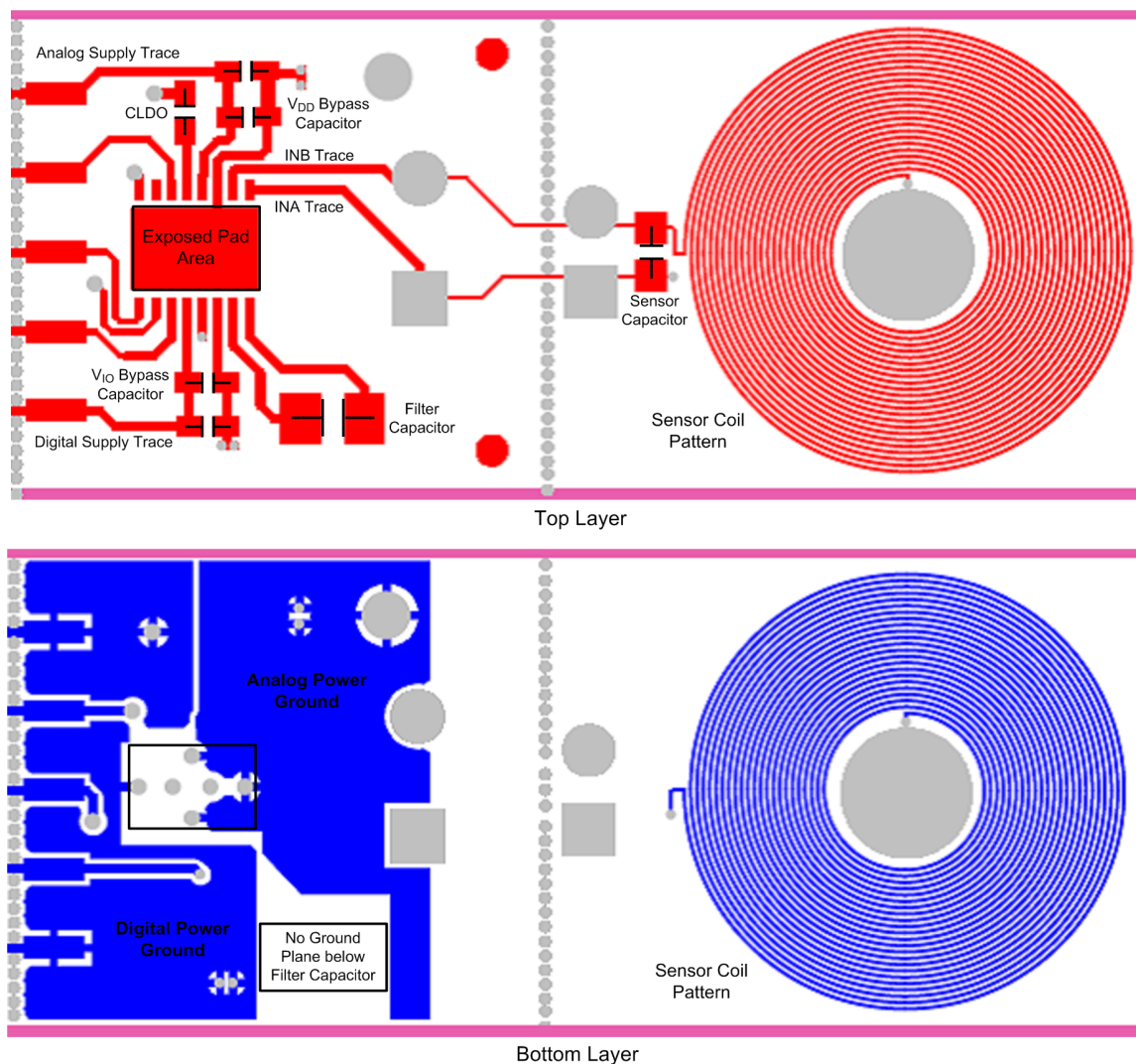
The LDC1041 is designed to operate from an analog supply range of 4.75 V to 5.25 V and digital I/O supply range of 1.8V to 5.25V. The analog supply voltage should be greater than or equal to the digital supply voltage for proper operation of the device. The supply voltage should be well regulated. If the supply is located more than a few inches from the LDC1041 additional bulk capacitance may be required in addition to the ceramic bypass capacitors. An electrolytic capacitor with a value of 10 $\mu$ F is a typical choice.

## 10 Layout

### 10.1 Layout Guidelines

- The VDD and VIO terminal should be bypassed to ground with a low ESR ceramic bypass capacitor. The typical recommended bypass capacitance is 0.1 $\mu$ F ceramic with a X5R or X7R dielectric.
- The optimum placement is closest to the VDD/VIO and GND/DGND terminals of the device. Care should be taken to minimize the loop area formed by the bypass capacitor connection, the VDD/VIO terminal, and the GND/DGND terminal of the IC. See [Figure 23](#) for a PCB layout example.
- The CLDO terminal should be bypassed to digital ground (DGND) with a 56nF ceramic bypass capacitor.
- The filter capacitor selected for the application using the procedure described in section [Choosing Filter Capacitor \(CFA and CFB Terminals\)](#) is connected between CFA and CFB terminals. Place the filter capacitor close to the CFA and CFB terminals. Do not use any ground/power plane below the capacitor and the trace connecting the capacitor and the CFA /CFB terminals.
- Use of two separate ground plane for GND and DGND is recommended with a star connection. See [Figure 23](#) for a PCB layout example.

## 10.2 Layout Example



**Figure 23. LDC10xx Board Layout**

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## 11 Device and Documentation Support

### 11.1 Trademarks

All trademarks are the property of their respective owners.

### 11.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 11.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LDC1041NHRJ	ACTIVE	WSON	NHR	16	4500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LDC1041	<a href="#">Samples</a>
LDC1041NHRR	ACTIVE	WSON	NHR	16	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LDC1041	<a href="#">Samples</a>
LDC1041NHRT	ACTIVE	WSON	NHR	16	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LDC1041	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**PACKAGE OPTION ADDENDUM**

17-May-2014

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## PACKAGE MATERIALS INFORMATION

### TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LDC1041NHRJ	WSON	NHR	16	4500	330.0	12.4	4.3	5.3	1.3	8.0	12.0	Q1
LDC1041NHRR	WSON	NHR	16	1000	178.0	12.4	4.3	5.3	1.3	8.0	12.0	Q1
LDC1041NHRT	WSON	NHR	16	250	178.0	12.4	4.3	5.3	1.3	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

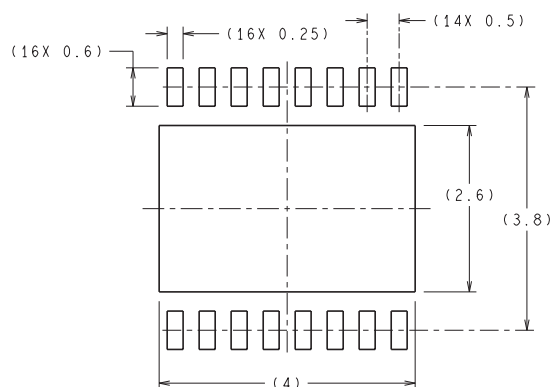


\*All dimensions are nominal

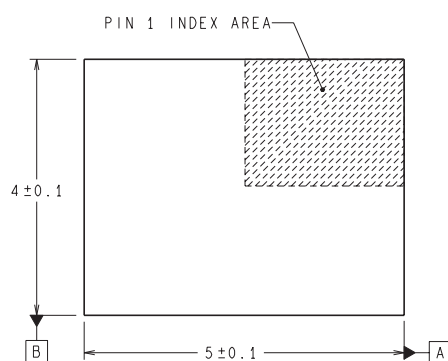
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LDC1041NHRJ	WSON	NHR	16	4500	367.0	367.0	35.0
LDC1041NHRR	WSON	NHR	16	1000	210.0	185.0	35.0
LDC1041NHRT	WSON	NHR	16	250	210.0	185.0	35.0

## MECHANICAL DATA

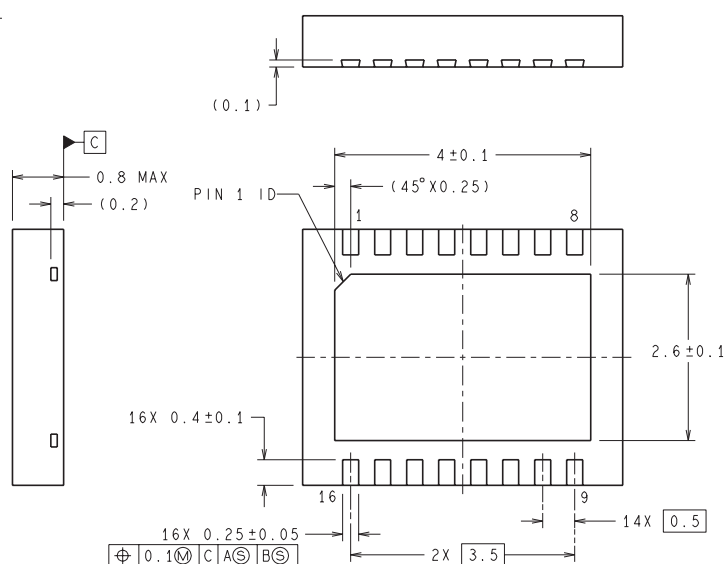
NHR0016B



## RECOMMENDED LAND PATTERN



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SDA16B (Rev A)

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